

Abstract

A device and method are provided for preventing a protruding electrode from being melted during mounting of a carrier substrate. A first protruding electrode whose melting point is lower than that of a second protruding electrode is provided on a land that is formed on the back surface of a carrier substrate. The first protruding electrode is bonded on a land on a mother substrate by reflow processing at a temperature that is lower than the melting point of the second protruding electrode and higher than the melting point of the first protruding electrode.